

# SN54LS266, SN74LS266 QUADRUPLE 2-INPUT EXCLUSIVE-NOR GATES WITH OPEN-COLLECTOR OUTPUTS

SDLS151 - DECEMBER 1972 - REVISED MARCH 1988

- Can Be Used as a 4-Bit Digital Comparator
- Input Clamping Diodes Simplify System Design
- Fully Compatible with Most TTL Circuits

FUNCTION TABLE

INPUTS		OUTPUT
A	B	Y
L	L	H
L	H	L
H	L	L
H	H	H

H = high level, L = low level

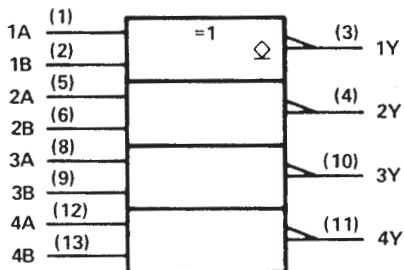
## description

The 'LS266 is comprised of four independent 2-input exclusive-NOR gates with open-collector outputs. The open-collector outputs permit tying outputs together for multiple-bit comparisons.

## logic symbol (each gate)



## logic symbol†



positive logic:  $Y = \overline{A \oplus B} = AB + \overline{AB}$

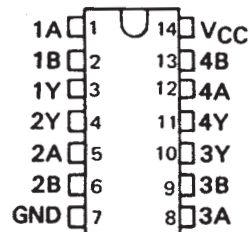
† This symbol is in accordance with ANSI/IEEE Std. 91-1984 and IEC Publication 617-12.

Pin numbers shown are for D, J, N, and W packages.

SN54LS266 . . . J OR W PACKAGE

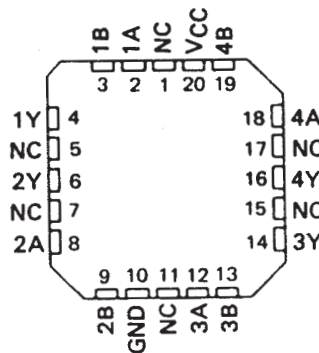
SN74LS266 . . . D OR N PACKAGE

(TOP VIEW)



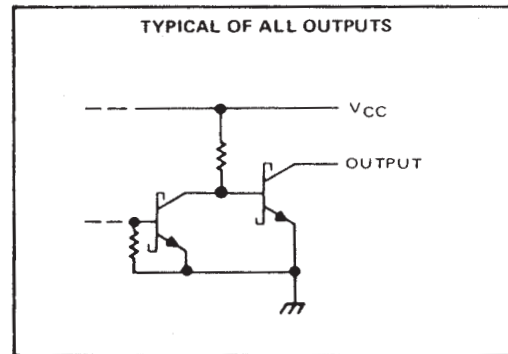
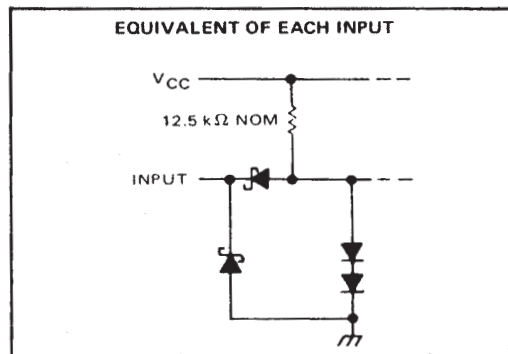
SN54LS266 . . . FK PACKAGE

(TOP VIEW)



NC - No internal connection

## schematic of inputs and outputs



# SN54LS266, SN74LS266 QUADRUPLE 2-INPUT EXCLUSIVE-NOR GATES WITH OPEN-COLLECTOR OUTPUTS

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## absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage, $V_{CC}$ (see Note 1)	7 V
Input voltage	7 V
Operating free-air temperature range: SN54LS266	-55°C to 125°C
SN74LS266	0°C to 70°C
Storage temperature range	-65°C to 150°C

NOTE 1: Voltage values are with respect to network ground terminal.

## recommended operating conditions

	SN54LS266			SN74LS266			UNIT
	MIN	NOM	MAX	MIN	NOM	MAX	
Supply voltage, $V_{CC}$	4.5	5	5.5	4.75	5	5.25	V
High-level output voltage, $V_{OH}$			5.5			5.5	V
Low-level output current, $I_{OL}$			4			8	mA
Operating free-air temperature, $T_A$	-55		125	0		70	°C

## electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS†	SN54LS266			SN74LS266			UNIT
		MIN	TYP‡	MAX	MIN	TYP‡	MAX	
$V_{IH}$ High-level input voltage		2			2			V
$V_{IL}$ Low-level input voltage				0.7			0.8	V
$V_{IK}$ Input clamp voltage	$V_{CC} = \text{MIN}, I_I = -18 \text{ mA}$			-1.5			-1.5	V
$I_{OH}$ High-level output current	$V_{CC} = \text{MIN}, V_{IH} = 2 \text{ V}, V_{IL} = V_{IL \text{ max}}, V_{OH} = 5.5 \text{ V}$			100			100	μA
$V_{OL}$ Low-level output voltage	$V_{CC} = \text{MIN}, V_{IH} = 2 \text{ V}, V_{IL} = V_{IL \text{ max}}, I_{OL} = 4 \text{ mA}$		0.25	0.4		0.25	0.4	V
	$I_{OL} = 8 \text{ mA}$					0.35	0.5	
$I_I$ Input current at maximum input voltage	$V_{CC} = \text{MAX}, V_I = 7 \text{ V}$			0.2			0.2	mA
$I_{IH}$ High-level input current	$V_{CC} = \text{MAX}, V_I = 2.7 \text{ V}$			40			40	μA
$I_{IL}$ Low-level input current	$V_{CC} = \text{MAX}, V_I = 0.4 \text{ V}$			-0.8			-0.8	mA
$I_{CC}$ Supply current	$V_{CC} = \text{MAX}, \text{ See Note 2}$		8	13		8	13	mA

† For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions for the applicable type.

‡ All typical values are at  $V_{CC} = 5 \text{ V}, T_A = 25^\circ \text{C}$ .

NOTE 2:  $I_{CC}$  is measured with one input of each gate at 4.5 V, the other inputs grounded, and the outputs open.

## switching characteristics, $V_{CC} = 5 \text{ V}, T_A = 25^\circ \text{C}$

PARAMETER§	FROM (INPUT)	TEST CONDITIONS		MIN	TYP	MAX	UNIT
$t_{PLH}$	A or B	Other input low	$C_L = 15 \text{ pF}, R_L = 2 \text{ k}\Omega, \text{ See Note 3}$		18	30	ns
$t_{PHL}$					18	30	
$t_{PLH}$	A or B	Other input high			18	30	ns
$t_{PHL}$					18	30	

§  $t_{PLH}$  = propagation delay time, low-to-high-level output

$t_{PHL}$  = propagation delay time, high-to-low-level output

NOTE 3: Load circuits and voltage waveforms are shown in Section 1.



**PACKAGING INFORMATION**

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
SN54LS266J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	SN54LS266J	<a href="#">Samples</a>
SN74LS266D	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS266	<a href="#">Samples</a>
SN74LS266DG4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS266	<a href="#">Samples</a>
SN74LS266N	ACTIVE	PDIP	N	14	25	Green (RoHS & no Sb/Br)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74LS266N	<a href="#">Samples</a>
SNJ54LS266J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	SNJ54LS266J	<a href="#">Samples</a>
SNJ54LS266W	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	SNJ54LS266W	<a href="#">Samples</a>

(1) The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

**RoHS Exempt:** TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

**Green:** TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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**OTHER QUALIFIED VERSIONS OF SN54LS266, SN74LS266 :**

- Catalog: [SN74LS266](#)
- Military: [SN54LS266](#)

NOTE: Qualified Version Definitions:

- Catalog - TI's standard catalog product
- Military - QML certified for Military and Defense Applications

W (R-GDFP-F14)

CERAMIC DUAL FLATPACK



- NOTES:
- All linear dimensions are in inches (millimeters).
  - This drawing is subject to change without notice.
  - This package can be hermetically sealed with a ceramic lid using glass frit.
  - Index point is provided on cap for terminal identification only.
  - Falls within MIL STD 1835 GDFP1-F14

J 14

**GENERIC PACKAGE VIEW**  
**CDIP - 5.08 mm max height**  
CERAMIC DUAL IN LINE PACKAGE



Images above are just a representation of the package family, actual package may vary.  
Refer to the product data sheet for package details.

4040083-5/G

J0014A



# PACKAGE OUTLINE

CDIP - 5.08 mm max height

CERAMIC DUAL IN LINE PACKAGE



4214771/A 05/2017

**NOTES:**

1. All controlling linear dimensions are in inches. Dimensions in brackets are in millimeters. Any dimension in brackets or parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This package is hermetically sealed with a ceramic lid using glass frit.
4. Index point is provided on cap for terminal identification only and on press ceramic glass frit seal only.
5. Falls within MIL-STD-1835 and GDIP1-T14.

# EXAMPLE BOARD LAYOUT

J0014A

CDIP - 5.08 mm max height

CERAMIC DUAL IN LINE PACKAGE



LAND PATTERN EXAMPLE  
NON-SOLDER MASK DEFINED  
SCALE: 5X



4214771/A 05/2017



D (R-PDSO-G14)

PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - $\triangle C$  Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
  - $\triangle D$  Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
  - E. Reference JEDEC MS-012 variation AB.

D (R-PDSO-G14)

PLASTIC SMALL OUTLINE



4211283-3/E 08/12

- NOTES:
- All linear dimensions are in millimeters.
  - This drawing is subject to change without notice.
  - Publication IPC-7351 is recommended for alternate designs.
  - Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
  - Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

N (R-PDIP-T\*\*)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
  - The 20 pin end lead shoulder width is a vendor option, either half or full width.

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